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Intellectual Property Law

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Date: Sept. 26, 2003

TO: Examiner Richard A. Booth (703) 872-9319  
Art Unit: 2812

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Subject Matter: 09/ 920,911 Attorney Doc: 67,200-506

Message:

Total number of pages sent: - 12 - (including this cover sheet)

67,200-506; TSMC 00-804  
Serial Number 09/920,911

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**TO:** Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**FROM:** Tung & Associates  
838 West Long Lake Road - Suite 120  
Bloomfield Hills, MI 48302

**DATE:** 9 September 2003

**REF:** Applicant : Yu et al. Filing Date : 2 August 2001  
Serial No : 09/920,911 Att'y No. : 67,200-506  
Art Unit : 2812 Examiner : Richard A. Booth  
Title : Thermal Compensation Method for Forming Semiconductor  
Integrated Circuit Microelectronic Fabrication

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**AMENDMENT AND RESPONSE TO OFFICE ACTION MADE FINAL**

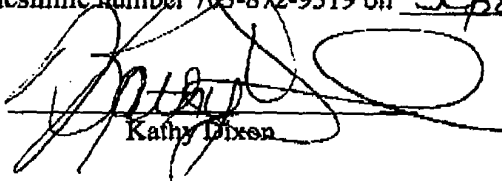
Sir:

In response to an office action mailed on 4 August 2003 and made FINAL, please consider the following amendments and remarks directed towards the above referenced patent application.

There are no amendments to the specification, claims or the drawings. A Listing of the Claims (having claim amendments therein) begins on page 2 of this paper. Remarks begin on page 6 of this paper.

**CERTIFICATE OF FACSIMILE TRANSMISSION**

I hereby certify that this correspondence is being facsimile transmitted to the United States Patent and Trademark Office at facsimile number 703-872-9319 on Sept. 26 2003.

  
Kathy Dixon